Unapproved Minutes

IEEE P802.3db 100 Gb/s, 200 Gb/s, and 400 Gb/s Short Reach Fiber Task Force Interim Meeting

Webex Meeting
January 21, 2021
Prepared by Mabud Choudhury

Group Name: IEEE P802.3db 100 Gb/s, 200 Gb/s, and 400 Gb/s Short Reach Fiber Task Force
Date/Location: Thursday, January 21, 2021. Webex meeting.
Chair: Robert Lingle, Jr (OFS)
Editors: Ramana Murty (Broadcom), Earl Parsons (CommScope)
Recording Secretary: Mabud Choudhury (OFS)
Meeting Participants: Attendance is listed in Appendix A (65 attendees – based on official IMAT attendance list; 71 Webex attendees)

Call to order:
IEEE P802.3db 100 Gb/s, 200 Gb/s, and 400 Gb/s Short Reach Fiber Task Force (TF) Interim WebEx meeting was convened at 12:01 PM Eastern Standard Time (EST/ UTC -5), Thursday, January 21, 2021 by Robert Lingle, Jr., P802.3db TF Chair.

Webex Meeting Procedures:
He instructed attendees to either add their affiliations to their names in the Webex participants list, or else list their name with affiliation in the chat window – a meeting requirement. [These two instructions were repeated multiple times throughout the meeting].

Chair's Presentation:
Title: "Agenda and General Information"
Presenter: Robert Lingle, Jr. (OFS)
agenda_3db_01a_0121.pdf (version 01a updates with correct link for Objectives on slide 30)

Mr. Lingle then proceeded with reviewing the **Agenda**, Slide 3 of agenda_3db_01a_0121.pdf, and asked if there any modifications, additions or deletions? There were none.

.3db Motion #1:
Move to approve the Agenda for Interim TF Teleconference, Slide 3 of agenda_3db_01_0121.pdf

- M: John Abbott
- S: Mike Dudek
- (Procedural > 50%)
- Motion passed by unanimous consent

Agenda approved at 12:04 PM

Approved Agenda:

- Welcome
- Approve Agenda
- Attendance
- Approve Meeting Minutes for November Plenary

- Goals for this meeting
- Reflector and Web
- Ground Rules
- IEEE
- Structure, Bylaws and Rules
  - Call for Patents. IEEE Patent Policy reminder: http://www.ieee802.org/3/patent.html
  - IEEE Copyright reminder: https://standards.ieee.org/ipr/index.html
  - IEEE Participant reminder: http://www.ieee802.org/devdocs.shtml
  - IEEE Standards Process
  - PAR & Objectives
- Baseline Proposal & Contribution
- Straw Polls & Motions
- Future Meetings

Attendance: Chair asked attendees to use http://imat.ieee.org/ to record attendance and provided Session Code for the IEEE 802.3 WG Interim Week 1 meetings and reviewed the IMAT steps to log attendance for this TF meeting. Attendance record based on IMAT only.

Approved Meeting Minutes: Mr. Choudhury explained the reason for updating unapproved meeting minutes, version 01a, for December 17, 2020 TF ad hoc meeting. Mr. Lingle asked if there were any updates/corrections to updated December 17 unapproved minutes or to November Plenary unapproved minutes. There were none. The motion wording was corrected from Interim to Plenary for the November meeting minutes.

.3db Motion #2:

Move to approve meeting minutes for:

  - November 10 & 12, 2020 IEEE P802.3db 100 Gb/s, 200 Gb/s, and 400 Gb/s Short Reach Fiber TF Plenary meeting: unapproved_meeting_minutes_3db_01_1120.pdf
  - December 17, 2020 IEEE P802.3db 100 Gb/s, 200 Gb/s, and 400 Gb/s Short Reach Fiber TF Telephonic Ad Hoc meeting: unapproved_minutes_3db_adhoc_01a_121720.pdf

- M: John Abbott
- S: Ramana Murty
- (Procedural > 50%)
- Motion passed by unanimous consent

Task Force Decorum: Chair asked for attendees to stay on mute when not speaking. Chair asked if anyone from the **Press** was present – no one indicated that they were from the Press.

Mr. Lingle provided **Goal for the meeting:** Review, discussion, progress, update on consensus building to adopt Baseline Proposal.

Reflector and Web: Chair showed the links to the IEEE 802.3db 100 Gb/s, 200 Gb/s, and 400 Gb/s Short Reach Fiber Task Force page, and the email reflector.

Chair reviewed:
Ground Rules: slide 11 of agenda_3db_01a_0121.pdf
IEEE Structure: slide 12 of agenda_3db_01a_0121.pdf

Important Bylaws and Rules: slide 13 of agenda_3db_01a_0121.pdf

Chair had shared the IEEE SA Patent, Copyright and Participation Policies prior to the meeting and had asked participants to be familiar these policies. Mr. Lingle asked if any participants had questions, and that there were no questions.

IEEE SA Patent Policy: Mr. Lingle provided overview of slides 14-18 of agenda_3db_01a_0121.pdf. at 12:13 PM.

IEEE SA Copyright Policy: Mr. Lingle showed slides 19-21 of agenda_3db_01a_0121.pdf entitled "IEEE SA Copyright Policy" overview

IEEE SA Participation Policy: Mr. Lingle showed the participation policy overview slides 22-24 of agenda_3db_01a_0121.pdf .

Mr. Lingle then reviewed the Overview of IEEE 802.3 Standards Process – completed Study Group Phase, and now in Task Force Comment Phase (slide 26 of agenda_3db_01a_0121.pdf).

Chair showed links for Approved Project Documents: PAR, CSD and Objectives slide 30 of agenda_3db_01a_0121.pdf). Mr. Lingle then showed the TF Objectives and Timeline.

Chair reviewed selection of Baselines overview.

Contribution #1:
Title: "Link performance and baseline analysis"
Presenter: Youxi Lin (affiliated with Huawei)
lin_3db_01a_0121.pdf
(version 01a, posted after the meeting, updates slide 5 to indicate charts/data that are simulated, based on feedback during meeting)

- Presentation provided:
    - ER and RIN_OMA evaluation – simulated data. Impact on system margin is suggested to be investigated.
    - Interoperability concerns based on: significant change to effective ref. receiver bandwidth as fiber increases from back-to-back to 100m; pre-emphasis aiming at 100m will cause overshoot at short distance; overshoot may further induce error floor penalty. The remarks on overshoot (slide 6) were presented with a measurement on a 50 Gb/s link.
- Technical discussion followed.
- Topics discussed included: ER being TBD, ER and RIN_OMA - what is in the spec. vs. vendor choice; TDECQ vs ER and RIN, method for changing ER; clarifying measured vs. simulated data for slide 6; accounting for impact of VCSEL non-linearity - lower ER leads to less distortion and lower TDECQ; for slide 5, TDECQ vs. RIN shown as opposed to TDECQ vs. RIN_OMA.
- Clarifying questions asked and answered.
- Author welcomed feedback from the group.

Chair requested additional contributions and consensus building to adopt updated baseline proposal.

Future meetings:

- See: http://ieee802.org/3/calendar.html and http://ieee802.org/3/interims/index.html
- P802.3db TF Ad Hoc Teleconferences are currently scheduled:

Biweekly on Thursdays at 12 Noon to 2 pm Eastern US (EST/UTC -5):
http://www.ieee802.org/3/db/public/adhoc/index.html
Next Ad Hoc meeting: Thursday, February 4, 2021, 12 Noon to 2 pm Eastern US (EST/UTC -5)

- Ad hoc meetings will be converted to TF interims when TF business requires

On TF interim teleconferences, only 802.3 voters may vote on TF motions

- March IEEE 802 LMSC plenary will be electronic only, 5 March - 19 March 2021

March IEEE 802.3 WG plenary session schedule is yet to be announced
P802.3db TF plenary teleconferences yet to be announced for March 2021

The Task Force Interim meeting was adjourned at 1:12 PM EST/ UTC -5, Thursday, January 21, 2021.

.3db Motion #3:
Move to Adjourn TF Telephonic Interim Meeting

- M: Mike Dudek
- S: James Young
- (Procedural > 50%)
- Motion passes by unanimous consent

Next Meeting:
Scheduled P802.3db TF Ad Hoc Webex meeting for Thursday, February 4, 2021 at 12:00 Noon – 2:00 PM EST/UTC -5.

Appendix A: Attendance List IEEE P802.3db Task Force WebEx Interim Meeting

65 individuals attended on Thursday, 21 January 2021, 12:01 PM – 1:12 PM EST/UTC -5

	Name	Employer	Affiliation
1	Abbott, John	Corning Incorporated	Corning Incorporated
2	Akbaba, Enis	Maxim Integrated Products	Maxim Integrated Products
3	Bhatt, Vipul	Finisar Corporation	Finisar Corporation
4	Bruckman, Leon	HUAWEI	HUAWEI
5	Calvin, John	Keysight Technologies	Keysight Technologies
6	Chang, Yongmao	Inphi Corporation	Source Photonics
7	Chen, Chan	Applied Optoelectronics, Inc.	Applied Optoelectronics, Inc.
8	Choudhury, Mabud	OFS	OFS
9	Dawe, Piers J G	Mellanox Technologies	Nvidia
10	Deandrea, John	Finisar Corporation	Finisar Corporation
11	Didde, Stephen	Keysight Technologies	Keysight Technologies
12	Dube, Kathryn	UNH-IOL	UNH-IOL
13	Dudek, Michael	Marvell	Marvell
14	FAn, DAWEI	HUAWEI	Huawei Technologies Co., Ltd
15	Ferretti, Vincent	Corning Incorporated	Corning Incorporated
16	Feyh, German	Broadcom Corporation	Broadcom Corporation
17	Graba, James	Broadcom Corporation	Broadcom Corporation
18	He, Xiang	HUAWEI	HUAWEI
19	Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
20	Horner, Rita	Synopsys, Inc.	Synopsys, Inc.
21	Hoser, Mirko	II-VI Incorporated	II-VI Incorporated
22	Hu, Kangmin	Innogrit	Innogrit
23	Jackson, Kenneth	Sumitomo Electric Device Innovations, USA	Sumitomo Electric Industries, LTD
24	Jiang, Tong	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
25	Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
26	Kimber, Eric	Semtech Ltd	Semtech Ltd
27	Klempa, Michael	University of New Hampshire InterOperability Laboratory (UNH-IOL)	Amphenol Corporation
28	Latchman, Ryan	MACOM	MACOM
29	Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
30	Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
31	Ledentsov, Nikolay	VI Systems GmbH	VI Systems GmbH
32	Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
33	Li, Mike-Peng	Intel Corporation	Intel Corporation
34	Lingle, Robert	OFS	OFS
35	Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
36	Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
37	Maniloff, Eric	Ciena Corporation	Ciena Corporation
38	Marques, Flavio	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
39	McMillan, Larry	Western Digital Corporation	Western Digital Corporation
40	Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
41	Murty, Ramana	Broadcom Corporation	Broadcom Corporation
42	Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
43	Palkert, Thomas	EIC	Samtec-Macom
44	Parsons, Earl	CommScope, Inc.	CommScope, Inc.
45	Piehler, David	Dell	Dell
46	Pimpinella, Rick	Panduit Corp.	Panduit Corp.
47	Sambasivan, Sam	AT&T	AT&T
48	Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
49	Sivakolundu, Ramesh	Cisco Systems, Inc.	Cisco Systems, Inc.
50	Son, Yung Sung	Optomind Inc	Optomind Inc
51	Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
52	Sun, Junqing	Credo Semiconductor	Credo Semiconductor
53	Sun, Yi	OFS	OFS
54	Swanson, Steven	Corning Incorporated	Corning Incorporated
55	TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
56	Takayama, Kazuya	Nitto Denko Corporation	Nitto Denko Corporation
57	Tang, Yi	Cisco Systems, Inc.	Cisco Systems, Inc.
58	Thompson, lance	II-VI Incorporated	II-VI Incorporated
59	Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
60	Tracy, Nathan	TE Connectivity	TE Connectivity
61	Voss, Robert	Panduit Corp.	Panduit Corp.
62	Young, James	CommScope, Inc.	CommScope
63	Zhang, Bo	Inphi Corporation	Inphi Corporation
64	Zhiwei, Yang	ZTE Corporation	ZTE Corporation
65	Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.